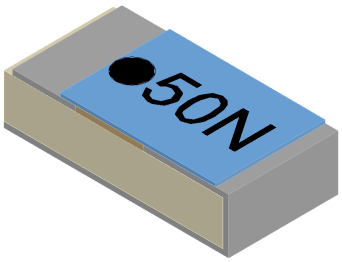
Model 100200N4X50-2

RF Power

Chip Termination
30 Watts, 50Ω



General Specifications

Resistive Element	Thick film
Substrate	AlN Ceramic
Terminals	Matte Tin over Nickel

Electrical Specifications

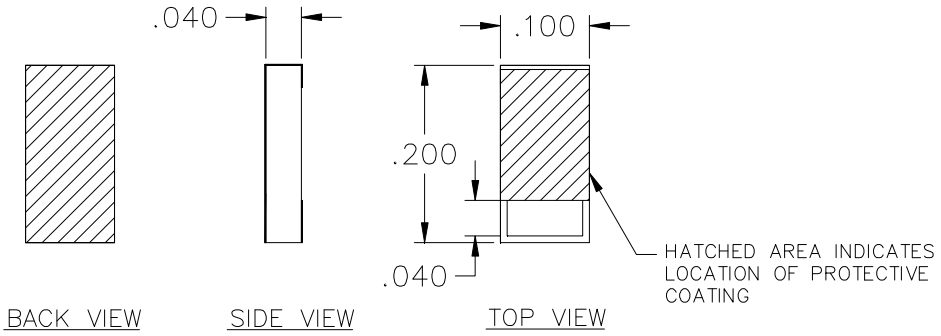
Resistance Range:	50 ohms, ± 2%
Frequency Range;	DC – 3.0 GHz
Power:	30 Watts
VSWR	1.25:1 DC – 3.0 GHz

Note: Tolerance is ±0.010", unless otherwise specified. Designed to meet of exceed applicable portions of MIL-E-5400. Operating temperature is -55ºC to 150ºC (see chart for derating temperatures).
All dimensions in inches.
Specifications subject to change with out notice.

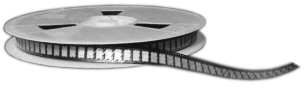
Features:

- **DC – 3.0 GHz**
- **30 Watts**
- **AlN Ceramic**
- **Non-Nichrome Resistive Element**
- **Low VSWR**
- **100% Tested**

Outline Drawing



100200N4X50-2 (097) Rev B



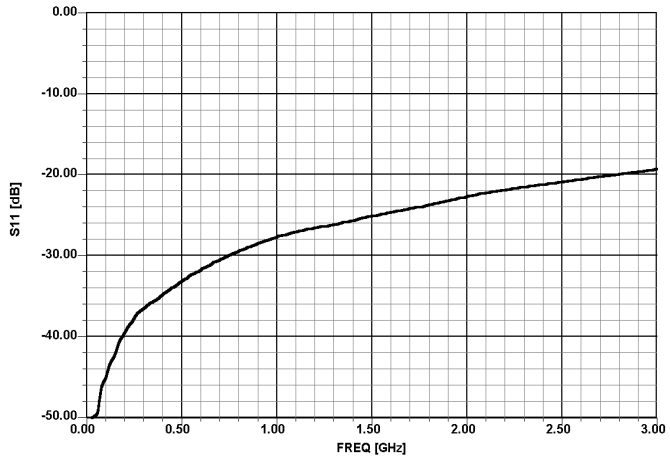
Available on Tape and Reel For Pick and Place Manufacturing.

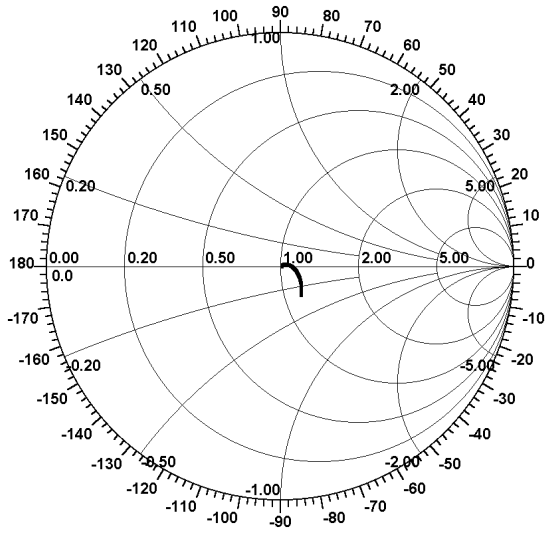
USA/Canada: (315) 432-8909
Toll Free: (800) 544-2414
Europe: +44 2392-232392

Model 100200N4X50-2

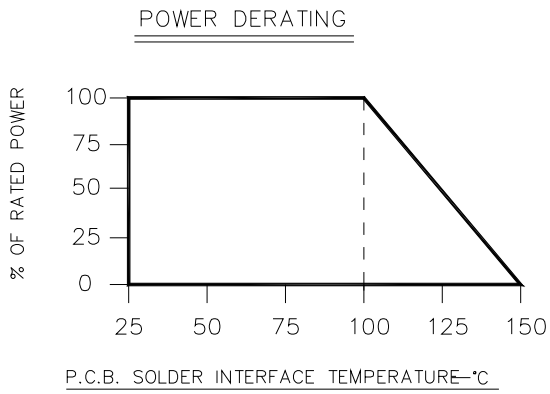
RF Power

Typical Performance:

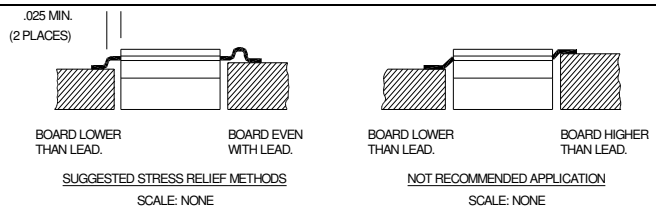




Power De-rating:



Mounting Footprint and Procedure:



SUGGESTED STRESS RELIEF METHODS
SCALE: NONE

NOT RECOMMENDED APPLICATION
SCALE: NONE

SUGGESTED MOUNTING PROCEDURES:

1. MAKE SURE THAT THE DEVICES ARE MOUNTED ON FLAT SURFACES (.001" UNDER THE DEVICE) TO OPTIMIZE THE HEAT TRANSFER.
2. DRILL & TAP THE HEATSINK FOR THE APPROPRIATE THREAD SIZE TO BE USED.
3. COAT HEATSINK WITH A MINIMUM AMOUNT OF HIGH QUALITY SILICONE GREASE (.001" MAX. THICKNESS).
4. POSITION DEVICE ON MOUNTING SURFACE & SECURE USING SOCKET HEAD SCREWS, FLAT & SPLIT WASHER. TORQUE SCREWS TO THE APPROPRIATE VALUE. MAKE SURE THAT THE DEVICE IS FLAT AGAINST THE HEATSINK. (CARE SHOULD BE TAKEN TO AVOID UPWARD PRESSURE OF THE LEADS TOWARDS THE LID).
5. SOLDER LEADS IN PLACE USING APPROPROATE SOLDER WITH A CONTROLLED TEMPERATURE IRON.

** FOR MORE DETAILS CONTACT FACTORY **

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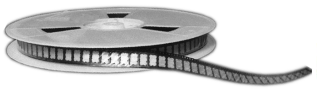

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What'll we think of next?™